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Claims

1. Optoelectronic component group which is mounted on a support (3) and which comprises at least two adjacent LEDs (2) at a prescribed distance (a), and also associated connecting lines (4), characterized in that the support (3) is composed of a material having a thermal conductivity of better than 1 W/Kxm, in particular of at least 1.5 W/Kxm.
2. Optoelectronic component group according to Claim 1, characterized in that the support is composed of a material which can be populated by means of SMD technology.
3. Optoelectronic component group according to Claim 1, characterized in that the support is composed of a material which is selected from the group consisting of ceramic, non-conducting cermet, plastic and/or composite material.
4. Optoelectronic component group according to Claim 1, characterized in that at least one further component (7) is fixed on the support.
5. Optoelectronic component group according to Claim 3, characterized in that the component is an electronic circuit, in particular an integrated circuit or complete drive circuit, or an LED.
6. Optoelectronic component group according to Claim 1, characterized in that the component group is a component part of a surface lighting luminaire or lamp.
7. Optoelectronic component group according to Claim 1, characterized in that a plurality of LEDs (2) are arranged regularly on the support.

8. Optoelectronic component group according to Claim 7, characterized in that the LEDs (2) form a section or an array, with a prescribed distance (a and b) in the rows and columns, respectively.

9. Optoelectronic component group according to Claim 6, characterized in that the distance between two adjacent LEDs is at most 5 mm, preferably less than 2 mm.

10. Optoelectronic component group according to Claim 1, characterized in that the support is mounted on a further heat-dissipating material, in particular a separate thermal plate or body parts of a vehicle.

11. Optoelectronic component group according to Claim 2, characterized in that further, in particular electronic component parts are integrated on the support.

12. Optoelectronic component group according to Claim 6, characterized in that the structural height of the group is less than 10 mm.

13. Optoelectronic component group which is mounted on a support (3) and which comprises at least two adjacent LEDs (2), which are spaced apart from one another, and also associated connecting lines (4), characterized in that the support (3) is composed of a material which dissipates heat well enough to realize a distance between adjacent LEDs of at most 5 mm, preferably less than 2 mm, without limiting the specified forward current of the LEDs and without further aids.

009290-2240960

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